New Product



Si4497DY

Vishay Siliconix

P-Channel 30 V (D-S) MOSFET

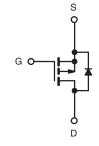
PRODUCT SUMMARY						
V _{DS} (V)	R _{DS(on)} (Ω)	I _D (A) ^d	Q _g (Typ.)			
- 30	0.0033 at V _{GS} = - 10 V	- 36	90 nC			
- 30	0.0046 at V_{GS} = - 4.5 V	- 29	30110			

FEATURES

- Halogen-free According to IEC 61249-2-21
 Definition
- TrenchFET[®] Power MOSFET
- 100 % Rg Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC

APPLICATIONS

- Adaptor Switch
- High Current Load Switch
- Notebook



P-Channel MOSFET

SO-8 s 8 D 1 D S 2 7 S 6 D 3 G D 5

Top View

Ordering Information: Si4497DY-T1-GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 30	V	
Gate-Source Voltage		V _{GS}	± 20	v	
	T _C = 25 °C		- 36		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 29		
Continuous Drain Current $(1) = 150^{\circ} C)$	T _A = 25 °C	I _D	- 24.8 ^{a, b}		
	T _A = 70 °C		- 19.2 ^{a, b}	Α	
Pulsed Drain Current	I _{DM}	- 70	A		
Continuous Courses Drain Diada Current	T _C = 25 °C		- 6.5		
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	- 2.9 ^{a, b}		
Avalanche Current		I _{AS}	- 30		
Single-Pulse Avalanche Energy	L = 0.1 mH	E _{AS}	45	mJ	
	T _C = 25 °C		7.8		
Maximum Dawar Dissinction	T _C = 70 °C	Б	5.0	w	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.5 ^{a, b}	vv	
	T _A = 70 °C		2.2 ^{a, b}		
Operating Junction and Storage Temperature Rang	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter		Symbol	Typical	Maximum	Unit		
Maximum Junction-to-Ambient ^{a, c}	t ≤ 10 s	R _{thJA}	29	35	°C/W		
Maximum Junction-to-Foot	Steady State	R _{thJF}	13	16	C/W		

Notes:

a. Surface mounted on 1" x 1" FR4 board.

b. t = 10 s.

c. Maximum under Steady State conditions is 80 °C/W.

d. Based on T_C = 25 °C.



COMPLIANT HALOGEN

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Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = - 250 μA	- 30			V
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$			- 26		m)//00
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I _D = - 250 μA		5.5		mV/°C
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = -250 \ \mu A$	- 1.0		- 2.5	V
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 V, V_{GS} = \pm 20 V$			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = -30 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 \text{ °C}$			- 1 - 5	μA
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -10 \text{ V}, \text{ V}_{GS} = -10 \text{ V}$	- 30		0	А
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = -10 \text{ V}, \text{ I}_D = -20 \text{ A}$ $V_{GS} = -4.5 \text{ V}, \text{ I}_D = -15 \text{ A}$		0.0027	0.0033	Ω
Forward Transconductance ^a	g _{fs}	$V_{DS} = -10 \text{ V}, I_D = -20 \text{ A}$		75	0.00+0	S
Dynamic ^b	315					Ŭ
Input Capacitance	C _{iss}			9685		I I
Output Capacitance	C _{oss}	V _{DS} = - 15 V, V _{GS} = 0 V, f = 1 MHz		995		pF
Reverse Transfer Capacitance	C _{rss}			995		
Total Gate Charge	Qg	$V_{DS} = -15$ V, $V_{GS} = -10$ V, $I_{D} = -20$ A		190	285	1
Gate-Source Charge	Q _{gs}	V _{DS} = - 15 V, V _{GS} = - 4.5 V, I _D = - 20 A		90 27.5	135	nC
Gate-Drain Charge	Q _{gs} Q _{qd}	$v_{\rm DS} = -10 v, v_{\rm GS} = -4.0 v, v_{\rm D} = -20 A$		27.5		
Gate Resistance	R _a	f = 1 MHz	0.5	20.3	4.6	Ω
Turn-On Delay Time	t _{d(on)}		0.0	19	35	52
Rise Time	t _r	V _{DD} = - 15 V, R _I = 1.5 Ω		13	25	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong -10 \text{ A}, \text{ V}_{\text{GEN}} = -10 \text{ V}, \text{ R}_{\text{g}} = 1 \Omega$		115	200	-
Fall Time	t _f			25	50	
Turn-On Delay Time	t _{d(on)}			100	180	ns
Rise Time	t _r	$V_{DD} = -15 V, R_1 = 1.5 \Omega$		75	150	-
Turn-Off DelayTime	t _{d(off)}	$I_D \cong$ - 10 A, V_{GEN} = - 4.5 V, R_a = 1 Ω		100	180	
Fall Time	t _f			42	80	
Drain-Source Body Diode Characteris	•					
Continous Source-Drain Diode Current	۱ _S	T _C = 25 °C			- 36	
Pulse Diode Forward Current	I _{SM}	, , , , , , , , , , , , , , , , , , ,			- 70	A
Body Diode Voltage	V _{SD}	I _S = - 3 A, V _{GS} = 0 V		- 0.70	- 1.2	V
Body Diode Reverse Recovery Time	t _{rr}	5 55		31	60	ns
Body Diode Reverse Recovery Charge Q _{rr}				23	45	nC
Reverse Recovery Fall Time	t _a	$I_F = -10 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, \text{T}_J = 25 ^\circ\text{C}$		13		
Reverse Recovery Rise Time	t _b			18		ns

Notes:

a. Pulse test; pulse width \leq 300 $\mu s,$ duty cycle \leq 2 %.

b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



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24

 $V_{GS} = 4.5 V$

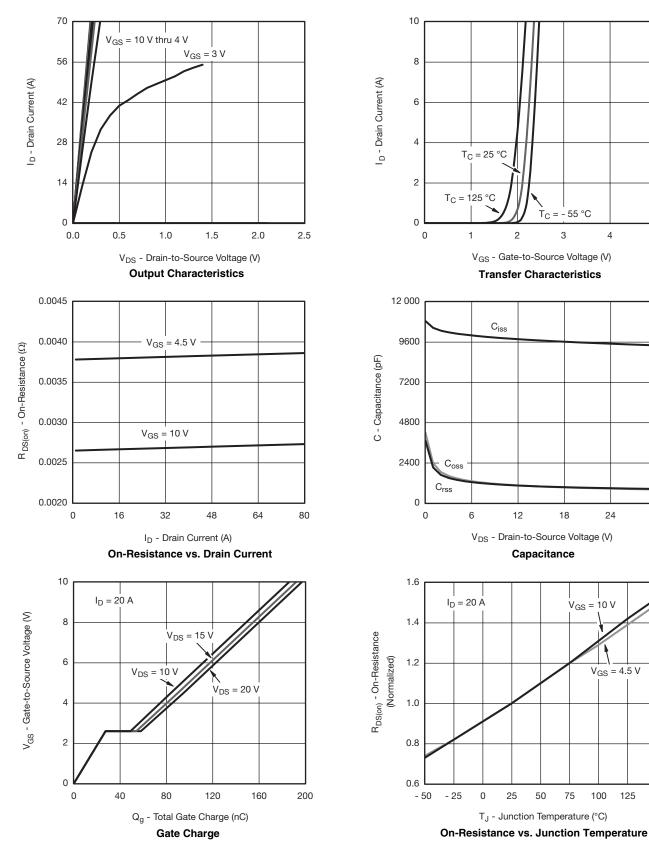
100

 $V_{GS} = 10 V$

30

5

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

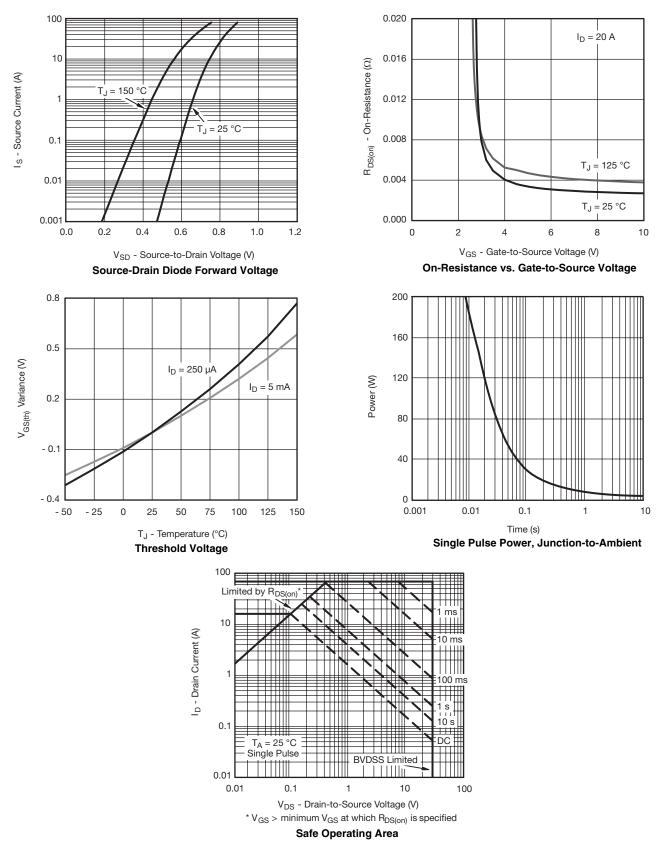


125 150

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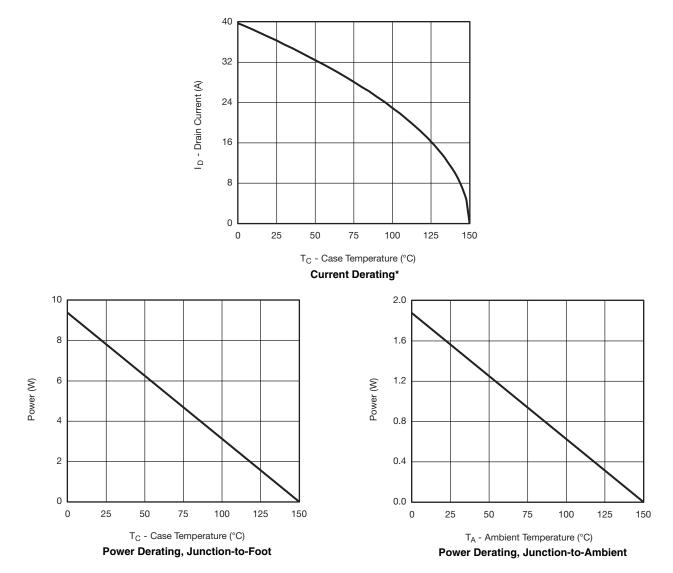
TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted





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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

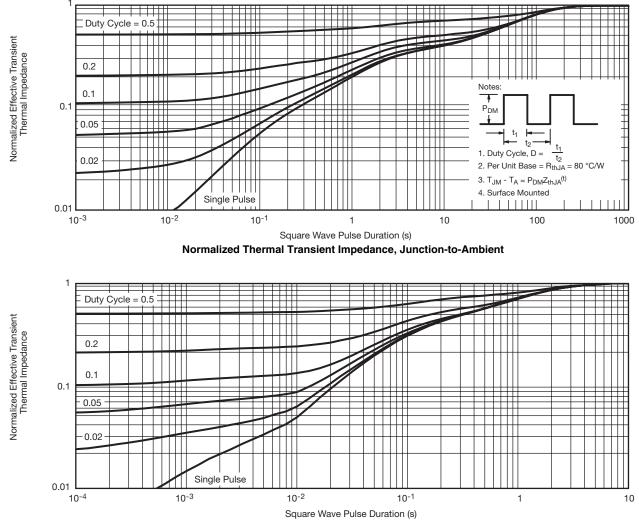


* The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



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TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Normalized Thermal Transient Impedance, Junction-to-Foot

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see www.vishay.com/ppg?65748.



Package Information

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SOIC (NARROW): 8-LEAD JEDEC Part Number: MS-012





	MILLIM	IETERS	INCHES			
DIM	Min	Мах	Min	Max		
A	1.35	1.75	0.053	0.069		
A ₁	0.10	0.20	0.004	0.008		
В	0.35	0.51	0.014	0.020		
С	0.19	0.25	0.0075	0.010		
D	4.80	5.00	0.189	0.196		
E	3.80	4.00	0.150	0.157		
е	1.27 BSC		0.050 BSC			
н	5.80	6.20	0.228	0.244		
h	0.25	0.50	0.010	0.020		
L	0.50	0.93	0.020	0.037		
q	0°	8°	0°	8°		
S	0.44	0.64	0.018	0.026		
ECN: C-06527-Rev. I, 11-Sep-06 DWG: 5498						

Application Note 826

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RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads Dimensions in Inches/(mm)

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